

REMARKS

Introduction

Claims 1-7 are pending, of which claims 1 and 4 are independent and claims 1-3 have been withdrawn. Claim 4 has been amended to correct informalities in the claim language and to more clearly define the claimed subject matter. Care has been taken to avoid introducing new matter.

Claim Rejection - 35 U.S.C. §103

Claims 4-6 have been rejected under 35 U.S.C. § 103(a) as being unpatentable over Maeda et al. (US 6,189,771) in view of Mei (US 6,680,128) and further in view of newly cited references, Kodas (US 6,951,666) and Kang et al (US 5,837,119). This rejection is traversed for at least the following reasons.

Applicants respectfully submit that amended claim 4 now recites, among other features, *“letting molten solder come in contact with the first electrode and the second electrode by melting the solder under heat and wetting and spreading it along surfaces of the metal powder guiding the molten solder.”* The flake-like shaped meal powder of the present subject matter has a function of guiding the molten solder in reflow process (see, page 3, lines 18-21 of the specification).

Turning to the cited references, at a minimum, it is clear that Maeda and Mei fail to disclose the use of flake-like shaped metal powder. Further, neither Kodas nor Kang discloses or suggests that the metal powder has a function of guiding the molten solder in the reflow process. Although Kang appears to disclose that flake-like powders are used because of their higher aspect ratios allowing for better electrical conditions, Kang fails to disclose the guiding function

of the flake-like powders. Therefore, the combination of Kudas and Kang with Maeda and Mei does not render claim 4 or any claim dependent thereon obvious, because none of the cited references disclose, recognize or suggest the function of guiding the molten solder of the flake-like metal powder.

Further, Applicants respectfully submit that Kudas is directed to a precursor composition for depositing or coatings of conductive materials (see, col. 1, lines 16-35 of Kudas), but is not directed to a soldering method or solders. As such, Kudas is not analogous art to the present subject matter and thus it would not have been obvious to combine Maeda, Mei and Kang with Kudas.

Based on the foregoing, claims 4-7 are patentable over the cited references. Thus, it is respectfully requested that the Examiner withdraw the rejection of claims 4-7 under 35 U.S.C. § 103(a).


Conclusion

Having fully responded to all matters raised in the Office Action, Applicants submit that all claims are in condition for allowance, an indication for which is respectfully solicited. If there are any outstanding issues that might be resolved by an interview or an Examiner's amendment, the Examiner is requested to call Applicants' attorney at the telephone number shown below.

To the extent necessary, a petition for an extension of time under 37 C.F.R. 1.136 is hereby made. Please charge any shortage in fees due in connection with the filing of this paper, including extension of time fees, to Deposit Account 500417 and please credit any excess fees to such deposit account.

Respectfully submitted,

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